

# STYCAST 1090 CAT 9

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## PRODUCT DESCRIPTION

STYCAST 1090 CAT 9 provides the following product characteristics:

<b>Technology</b>	Epoxy
Appearance (Resin)	Black
Components	Two components - requires mixing
Mix Ratio, by weight - Resin : Hardener	100 : 9
Mix Ratio, by volume - Base : Hardener	100 : 7
Product Benefits	<ul style="list-style-type: none"> <li>• Low density syntactic foam</li> <li>• Low CTE</li> <li>• Low dielectric constant</li> <li>• Low shrinkage</li> <li>• Good moisture resistance</li> <li>• Excellent chemical resistance</li> <li>• Good physical strength</li> </ul>
<b>Cure</b>	Room temperature cure
<b>Application</b>	Encapsulation
Operating Temperature	-40 to 130 °C

STYCAST 1090 CAT 9 is designed for encapsulation and potting of electronic assemblies that require lower weight such as aerospace applications. STYCAST 1090 CAT 9 is also available in the colour white.

STYCAST 1090 CAT 9 passes NASA outgassing standards.

STYCAST 1090 with CAT 9 can be used with a variety of catalysts.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

### Part A Properties LOCTITE STYCAST 1090

Viscosity, Brookfield , 25 °C, mPa·s (cP):	
Speed 10 rpm, # 7	135,000
Specific Gravity	0.85
Shelf Life @ 25°C, months	12
Flash Point - See SDS	

### Part B Properties LOCTITE CAT 9

Viscosity @ 25 °C, mPa·s (cP)	80 to 105
Flash Point - See SDS	

## Mixed Properties

Mixed Viscosity, mPa·s (cP)	30,000
Specific Gravity	0.79
Working Time, 100 g mass, @ 25°C, minutes	45
Flash Point - See SDS	

## TYPICAL CURING PERFORMANCE

### Cure Schedule

16 to 24 hours @ 25°C or
4 to 6 hours @ 45°C or
1 to 2 hour @ 65°C

### Post Cure

**Post Cure:** 2 to 4 hours at the highest expected use temperature

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties :

Thermal Conductivity , W/(m·K)	0.19
Hardness, Shore D	80
Water Absorption 24 hours, %	0.55
Linear Shrinkage, cm/cm	0.001
Compressive Strength, psi	12,000
Flexural strength , ASTM D790	N/mm <sup>2</sup> 48 (psi) (7,000)
Tensile Strength, psi	3,000

### Electrical Properties:

Volume Resistivity @ 25°C, ohm-cm	>1×10 <sup>13</sup>
Dielectric Constant @ 1mHz	2.7
Dissipation Factor @ 1mHz	0.05

### Outgassing Properties:

Total Mass Loss, %	0.46
Collected Volatile Condensable Material, %	0.06

**GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

**DIRECTIONS FOR USE**

1. Complete cleaning of the substrates should be performed to remove contamination such as oxide layers, dust, moisture, salt and oils which can cause poor adhesion or corrosion in a bonded part.
2. Some separation of components is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use.
3. Accurately weigh resin and hardener into a clean container in the recommended ratio.
4. Blend components by hand, using a kneading motion, for 2 to 3 minutes. Scrape the bottom and sides of the mixing container frequently to produce a uniform mixture.
5. If possible, power mix for an additional 2 to 3 minutes. Avoid high mixing speeds. This can entrap excessive amounts of air. It can also cause overheating of the mixture, resulting in reduced working life.
6. To ensure a void-free embedment, vacuum deairing should be used to remove any entrapped air introduced during the mixing operation.
7. Pump-down or pull vacuum on the mixture to achieve an ultimate vacuum or absolute pressure of 1 to 5 torr or mm Hg. The foam will rise several times in the liquid height and then subside.
8. Continue vacuum deairing until most of the bubbling has ceased. This usually takes 3 to 10 minutes.
9. To facilitate deairing in difficult to deair materials, add a few drops of an air release agent, such as ANTIFOAM 88 into 100 grams of mixture.
10. Gentle warming will also help, but pot life will be shortened.
11. Pour mixture into cavity or mold.
12. Gentle warming of the mold or assembly reduces the viscosity. This improves the flow of the material into the unit having intricate shapes or tightly packed coils or components.
13. Further vacuum deairing in the mold may be required for critical applications.

**STORAGE:**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage : 25 °C**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Certain resins and hardeners are prone to crystallization. If crystallization does occur, warm the contents of the shipping container to 50 to 60°C until all crystals have dissolved. Be sure the shipping container is loosely covered during the warming stage to prevent any pressure build-up. Allow contents to cool to room temperature before continuing.

**Not for product specifications**

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

**Disclaimer****Note:**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product. Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

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